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ELECTRICAL CHARACTERISTICS (@ 25°C unless otherwise specified)

	Symbol	1N6073 FF05	1N6074 FF10	1N6075 FF15	Unit
Average forward current max. (pcb mounted; T_A = 55°C)					
for sine wave	$I_{F(AV)}$	←	0.85	→	A
for square wave (d = 0.5)	$I_{F(AV)}$	←	0.90	→	A
Average forward current max.					
T_L = 70°C; L = 0".	$I_{F(AV)}$	←	3.0	→	A
T_L = 55°C; L = 3/8"					
for sine wave	$I_{F(AV)}$	←	1.7	→	A
for square wave	$I_{F(AV)}$	←	1.8	→	A
I^2t for fusing (t = 8.3mS) max.	I^2t	←	5.0	→	A^2S
Forward voltage drop max. @ I_F = 1.5A, T_j = 25°C	V_F	←	1.2	→	V
Reverse current max.					
@ V_{RWM}, T_j = 25°C	I_R	←	1.0	→	µA
@ V_{RWM}, T_j = 100°C	IR	←	50	→	µA
Reverse recovery time 0.5A I_F, 1.0A I_R, 0.25A I_{RR}.	t_{rr}	←	30	→	nS
Junction capacitance typ. @ V_R = 5V , f = 1MHz	C_j	←	28	→	pF

THERMAL CHARACTERISTICS

	Symbol	1N6073 FF05	1N6074 FF10	1N6075 FF15	Unit
Thermal resistance - junction to lead					
Lead length = 0.375"	$R_{\theta JL}$	←	46	→	°C/W
Lead length = 0.0"	$R_{\theta JL}$	←	13	→	°C/W
Thermal resistance - junction to amb. on 0.06" thick pcb. 1 oz. copper.	$R_{\theta JA}$	←	95	→	°C/W

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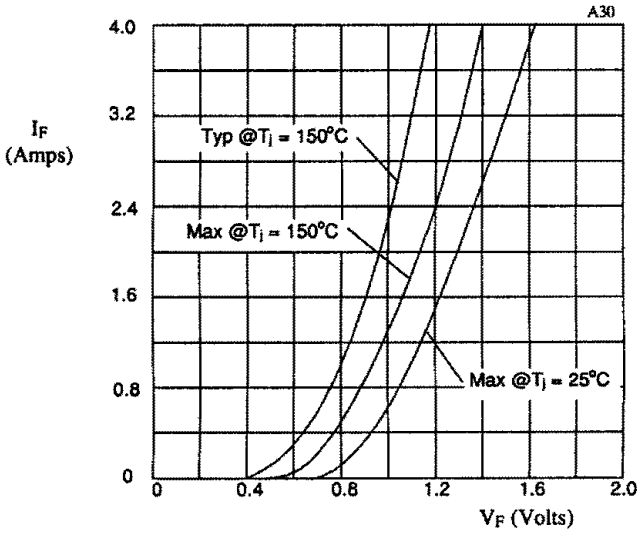

Fig 1. Forward voltage drop as a function of forward current.

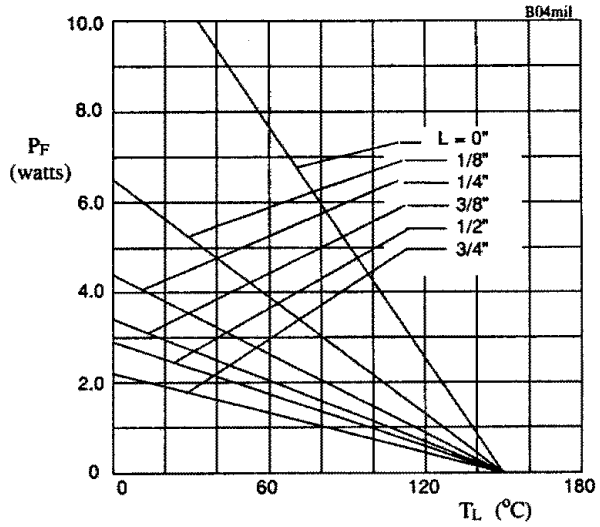

Fig 2. Maximum power versus lead temperature.

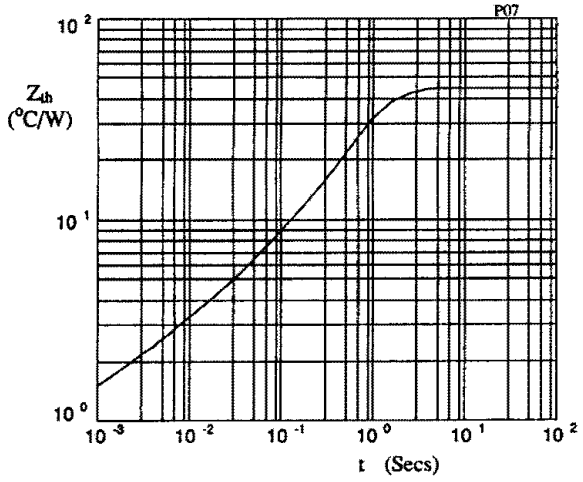

Fig 3. Transient thermal impedance characteristic.

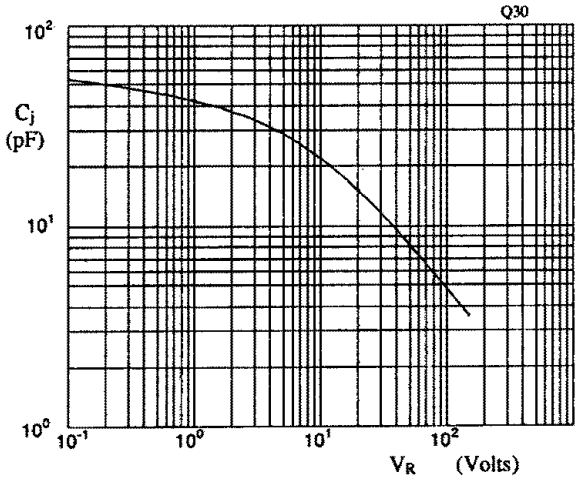

Fig 4. Typical junction capacitance as a function of reverse voltage.

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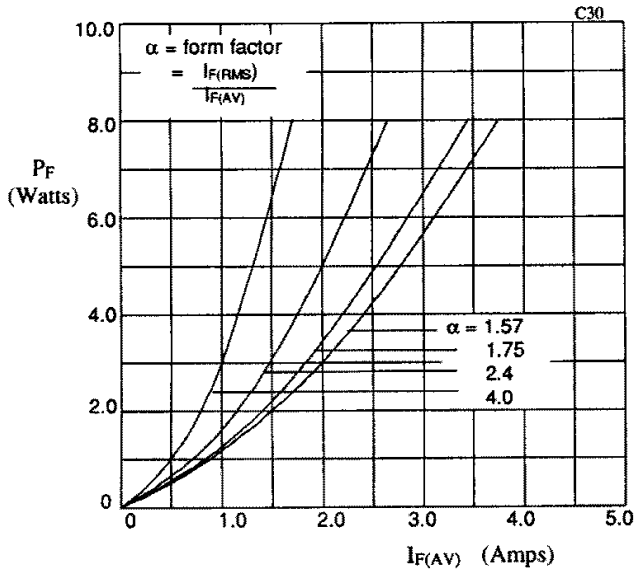

Fig 5. Forward power dissipation as a function of forward current, for sinusoidal operation.

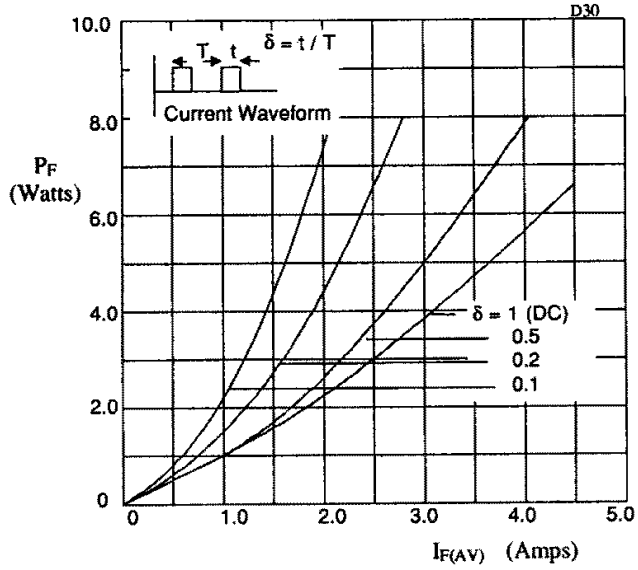

Fig 6. Forward power dissipation as a function of forward current, for square wave operation.

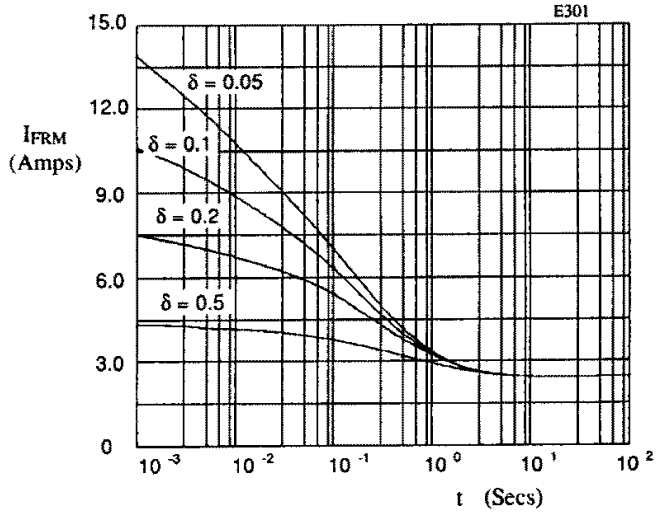

Fig 7. Maximum repetitive forward current as a function of pulse width at 55°C; $R_{\theta JL}$ = 45 °C/W; V_{RWM} during 1 - δ.

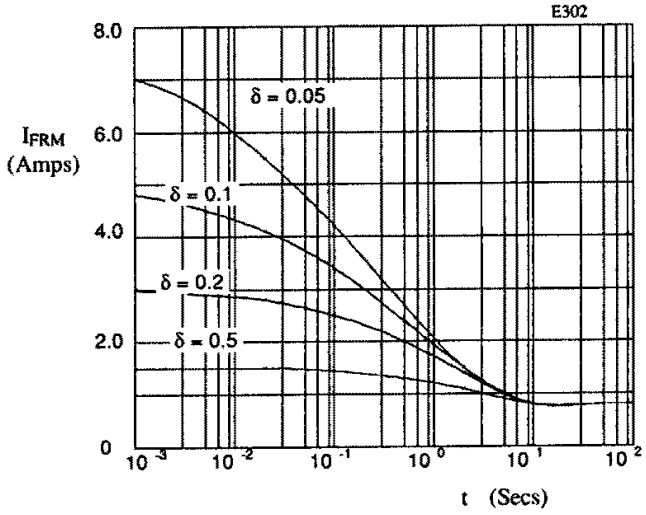

Fig 8. Maximum repetitive forward current as a function of pulse width at 100°C; $R_{\theta JL}$ = 110 °C/W; V_{RWM} during 1 - δ.